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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

APPLICANT: Zellner et al

SERIAL NO.: 09/786,512 GROUP ART UNIT: 1733

DATE FILED: February 28, 2001

INVENTION: "METHOD FOR PRODUCING METALLIC MICROSTRUCTURES" (As Amended)

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Assistant Commissioner for Patents
Washington, D.C. 20231

S I R:

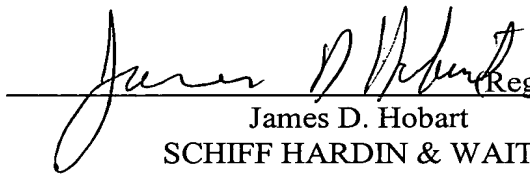
To comply with the Duty of Disclosure under 37 CFR 1.56, applicants' attorneys are mentioning the following:

The three inventors of the present application are also co-inventors of a PCT Application, which was published as WO 00/13130 (see attached cover page). As indicated, this was published subsequent to the International Filing Date of August 24, 1999 of the PCT Application of which the present application is a National Stage under 35 USC 371. Thus, the International Publication is not a reference against the present application.

The International Application is now owned by Infineon Technologies AG. It is the undersigned attorney's understanding that a National Stage Application was filed and replaced by a Continuation Application, U.S. Serial No. 09/796,214. The undersigned attorney

does not have access to that application; however, an amendment was filed in the present application on May 7, 2001 to cancel claim 27 and to limit the present application to the method, thus removing any possible conflict with the other application.

Respectfully submitted,



(Reg. No. 24,149)

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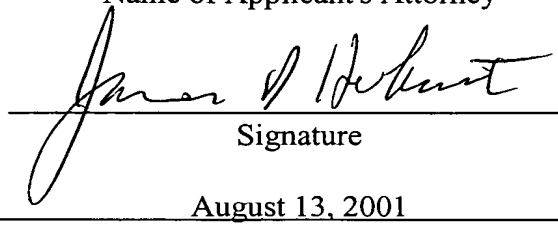
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CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service as First Class Mail in an envelope addressed to the Assistant Commissioner for Patents, Washington, D.C. 20231 on August 13, 2001.

James D. Hobart
Name of Applicant's Attorney



Signature

August 13, 2001
Date

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PCT

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INTERNATIONALE ANMELDUNG VERÖFFENTLICHT NACH DEM VERTRAG ÜBER DIE INTERNATIONALE ZUSAMMENARBEIT AUF DEM GEBIET DES PATENTWESENS (PCT)

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(81) Bestimmungsstaaten: BR, CN, IN, JP, KR, MX, RU, UA, US, europäisches Patent (AT, BE, CH, CY, DE, DK, ES, FI, FR, GB, GR, IE, IT, LU, MC, NL, PT, SE).

Veröffentlicht
Ohne internationalen Recherchenbericht und erneut zu veröffentlichen nach Erhalt des Berichts.

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(54) Title: SENSOR FIELD FOR CAPACITIVE MEASURING FINGERPRINT SENSOR AND METHOD FOR THE PRODUCTION OF SAID SENSOR FIELD

(54) Bezeichnung: SENSORFELD FÜR EINEN KAPAZITIV MESSENDEN FINGERPRINT–SENSOR UND VERFAHREN ZUR HERSTELLUNG EINES DERARTIGEN SENSORFELDES

(57) Abstract

First strip conductors (5), a first insulating layer (6), fine structures with first electrodes (51), two strip conductors (7), second electrodes (71) and finally a second insulating layer (8) are deposited one after the other on a base layer (3) that is preferably flexible. The first electrodes (51) are connected to the assigned strip conductors (5) by means of throughplatings. Changes caused by the cuticular sulci of a finger pad in the stray capacitance between adjacent first and second electrodes are evaluated to detect fingerprints.

(57) Zusammenfassung

Auf eine Basisschicht (3), die vorzugsweise flexibel ist, sind nacheinander erste Leiterbahnen (5), eine erste Isolationsschicht (6), Feinstrukturen mit ersten Elektroden (51), zweiten Leiterbahnen (7) und zweiten Elektroden (71) und abschließend eine zweite Isolationsschicht (8) aufgebracht. Die ersten Elektroden (51) sind über Durchkontaktierungen mit zugeordneten ersten Leiterbahnen (5) verbunden. Durch Hautlinien einer Fingerbeere verursachte Änderungen der Streukapazität zwischen benachbarten ersten und zweiten Elektroden werden für die Erfassung von Fingerabdrücken ausgewertet.

